

wherein the feeding position is moved on a ~~feeding plane~~ first surface when a high frequency electric power is fed to said first surface of said first electrode to form plasma, and.

wherein said moving mechanism substantially moves the feeding position of said feeding member on a circumference of a predetermined radius, which is concentric with said first electrode, on the first surface of said first electrode.

Claim 24 (cancelled)

Claim 25 (original): A plasma processing method as set forth in claim <sup>23</sup>~~24~~, wherein said feeding position moves at a moving speed of 20 rpm or higher.

Claim 26 (original): A plasma processing method for arranging a substrate to be processed, in a processing space between first and second electrodes provided so as to face each other, to supply a high frequency electric power to said first electrode while feeding a process gas into said processing space, to form plasma in said processing space to plasma-process said substrate,

wherein a plurality of receiving terminal portions are provided at positions other than the center on the opposite surface to the surface of said first electrode facing said second electrode, and a receiving terminal portion of said receiving terminal portions for receiving a high frequency electric power is sequentially switched when said high frequency electric power is fed to said first electrode to form plasma.